#### UMA1018M

#### FEATURES

- Low current from 3 V supply
- Fully programmable RF divider
- 3-line serial interface bus
- Second synthesizer to control first IF or offset loop frequency
- Independent fully programmable reference dividers for each loop, driven from external crystal oscillator
- Dual phase detector outputs to allow fast frequency switching
- Integrated digital-to-analog converter
- Dual power-down modes.

#### APPLICATIONS

- 900 MHz mobile telephones
- Portable battery-powered radio equipment.

#### GENERAL DESCRIPTION

The UMA1018M BICMOS device integrates prescalers, programmable dividers, and phase comparators to implement two phase-locked loops. The device is designed to operate from 3 NiCd cells, in pocket phones, with low current and nominal 5 V supplies.

The principal synthesizer operates at RF input frequencies up to1.25 GHz the auxiliary synthesizer operates at 300 MHz. The auxiliary loop is intended for the first IF or to transmit offset loop-frequency settings. Each synthesizer has a fully programmable reference divider. All divider ratios are supplied via a 3-wire serial programming bus.

Separate power and ground pins are provided to the analog and digital circuits. The ground leads should be externally short-circuited to prevent large currents flowing across the die and thus causing damage. Digital supplies  $V_{DD1}$  and  $V_{DD2}$  must also be at the same potential.  $V_{CC}$  must be equal to or greater than  $V_{DD}$  (i.e.  $V_{DD} = 3$  V and  $V_{CC} = 5$  V for wider tuning range).

The principal synthesizer phase detector uses two charge pumps, one provides normal loop feedback, while the other is only active during fast mode to speed-up switching. The auxiliary loop has a separate phase detector. All charge pump currents (gain) are fixed by an external resistance at pin  $I_{SET}$  (pin 14). Only passive loop filters are used; the charge-pumps function within a wide voltage compliance range to improve the overall system performance. An on-chip 7-bit DAC enables adjustment of an external function, such as the temperature compensation of a crystal oscillator in Global System for Mobile communications (GSM).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>CC</sub> , V <sub>DD</sub>	supply voltage	$V_{CC} \ge V_{DD}$	2.7	-	5.5	V
I <sub>CC</sub> + I <sub>DD</sub>	principal synthesizer supply current	auxiliary synthesizer in power-down mode	-	7.7	-	mA
	principal and auxiliary synthesizer supply current	principal and auxiliary synthesizers ON	-	10	-	mA
I <sub>CCPD</sub> , I <sub>DDPD</sub>	current in power-down mode per supply		-	12	-	μA
f <sub>VCO</sub>	principal input frequency		50	-	1250	MHz
f <sub>AI</sub>	auxiliary input frequency		20	_	300	MHz
f <sub>XTAL</sub>	crystal reference input frequency		3	_	40	MHz
f <sub>PPC</sub>	principal phase comparator frequency		-	200	-	kHz
f <sub>APC</sub>	auxiliary phase comparator frequency		-	200	-	kHz
T <sub>amb</sub>	operating ambient temperature		-30	—	+85	°C

#### QUICK REFERENCE DATA

#### UMA1018M

#### ORDERING INFORMATION

TYPE NUMBER		PACKAGE	
ITPE NOWBER	NAME	DESCRIPTION	VERSION
UMA1018M	SSOP20	plastic shrink small outline package; 20 leads; body width 4.4 mm	SOT266-1

#### **BLOCK DIAGRAM**



#### PINNING

SYMBOL	PIN	DESCRIPTION
FAST	1	control input to speed-up main synthesizer
CPPF	2	principal synthesizer speed-up charge-pump output
CPP	3	principal synthesizer normal charge-pump output
V <sub>DD1</sub>	4	digital power supply 1
V <sub>DD2</sub>	5	digital power supply 2
PRI	6	1 GHz principal synthesizer frequency input
DGND	7	digital ground
f <sub>XTAL</sub>	8	common crystal frequency input from TCXO
PON	9	principal synthesizer power-on input
DOUT	10	7-bit digital-to-analog output
CLK	11	Programming bus clock input
DATA	12	programming bus data input
Ē	13	programming bus enable input (active LOW)
I <sub>SET</sub>	14	regulator pin to set the charge-pump currents
AUX	15	auxiliary synthesizer frequency input
AGND	16	analog ground
СРА	17	auxiliary synthesizer charge-pump output
V <sub>CC</sub>	18	supply for charge-pump and DAC circuits
AON	19	auxiliary synthesizer power-on input
LOCK	20	in-lock detect output (main PLL); test mode output

#### FUNCTIONAL DESCRIPTION

#### Principal synthesizer

Programmable reference and main dividers drive the principal PLL phase detector. Two charge pumps produce phase error current pulses for integration in an external loop filter. A hardwired power-down input PON (pin 9) ensures that the dividers and phase comparator circuits can be disabled.

The PRI input (pin 6) drives a pre-amplifier to provide the clock to the first divider stage. The pre-amplifier has a high input impedance, dominated by pin and pad capacitance. The circuit operates with signal levels from 50 mV up to

225 mV (RMS), and at frequencies as high as 1.25 GHz. The high frequency divider circuits use bipolar transistors, slower bits are CMOS. Divider ratios (512 to 131 071) allow a 1 MHz phase comparison with a 500 MHz RF input, and a 10 kHz phase comparison with a 1.25 GHz RF input.

The reference and main divider outputs are connected to a phase/frequency detector that controls two charge pumps. The two pumps have a common bias-setting current that is set by an external resistance. The ratio between currents in fast and normal operating modes can be programmed via the 3-wire serial bus. The low current pump remains active except in power-down.



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## Low-voltage dual frequency synthesizer for radio telephones

The high current pump is enabled via the control input FAST (pin 1). By appropriate connection to the loop filter, dual bandwidth loops are provided: short time constant during frequency switching (FAST mode) to speed-up channel changes and low bandwidth in the settled state (on-frequency) to reduce noise and breakthrough levels.

The principal synthesizer speed-up charge pump (CPPF) is controlled by the FAST input in synchronization with phase detector operation in such a way that potential disturbances are minimized. The dead zone (caused by finite time taken to switch the current sources on or off) is cancelled by feedback from the normal pump output to the phase detector thereby improving linearity.

An open drain transistor drives the output pin LOCK (pin 20). It is recommended that the pull-up resistor from this pin to  $V_{DD}$  is chosen such that the value is high enough to keep the sink current in the LOW state below 400  $\mu$ A. The circuit can be programmed to output either the phase error in the principal or auxiliary phase detectors or the combination from both detectors (OR function). The resultant output will be a current pulse with the duration of the selected phase error. By appropriate external filtering and threshold comparison an out-of-lock or an in-lock flag is generated.

#### Auxiliary synthesizer

The auxiliary synthesizer has a 14-bit main divider and an 11-bit reference divider. A separate power-down input AON (pin 19), disables currents in the auxiliary dividers, phase detector, and charge pump. The auxiliary input signal is amplified and fed to the main divider. The input buffer presents a high impedance, dominated by pin and pad capacitance. First divider stages use bipolar technology operating at input frequencies up to 300 MHz; the slower bits are CMOS. The auxiliary loop phase detector and charge pump use similar circuits to the main loop low-current phase comparator, including dead-zone compensation feedback.

The auxiliary reference divider is clocked on the opposite edge of the principal reference divider to ensure that active edges arrive at the auxiliary and principal phase detectors at different times. This minimizes the potential for interference between the charge pumps of each loop.

#### Serial programming bus

A simple 3-line unidirectional serial bus is used to program the circuit. The 3 lines are DATA, CLK and  $\overline{E}$  (enable). The data sent to the device is loaded in bursts framed by  $\overline{E}$ . Programming clock edges and their appropriate data bits are ignored until  $\overline{E}$  goes active LOW. The programmed information is loaded into the addressed latch when  $\overline{E}$ returns inactive HIGH. Only the last 21 bits serially clocked into the device are retained within the programming register. Additional leading bits are ignored, and no check is made on the number of clock pulses. The fully static CMOS design uses virtually no current when the bus is inactive. It can always capture new programmed data even during power-down of main and auxiliary loops.

However, when either principal synthesizer or auxiliary synthesizer or both are powered-on, the presence of a TCXO signal is required at pin 8 ( $f_{XTAL}$ ) for correct programming.

#### Data format

Data is entered with the most significant bit first. The leading bits make up the data field, while the trailing four bits are an address field. The UMA1018M uses 6 of the 16 available addresses. These are chosen to allow direct compatibility with the UAA2072M integrated front-end. The data format is shown in Table 1. The first entered bit is p1, the last bit is p21.

The trailing address bits are decoded on the inactive edge of  $\overline{E}$ . This produces an internal load pulse to store the data in one of the addressed latches. To ensure that the data is correctly loaded on first power-up,  $\overline{E}$  should be held LOW and only taken HIGH after having programmed an appropriate register. To avoid erroneous divider ratios, the pulse is not allowed during data reads by the frequency dividers. This condition is guaranteed by respecting a minimum  $\overline{E}$  pulse width after data transfer. The corresponding relationship between data fields and addresses is given in Table 2.

	R BIT USAGE	p16	DATA1	
	PROGRAMMING REGISTER BIT USAGE	p17	DATA0	LSB
	PROGRAMM	p18	ADD3	
data		p19	ADD2	DRESS
of programmed data		p20	ADD1	LATCH ADDRESS

## Bit allocation (note 1) Table 2

Ŀ								RE	GISTE	R BIT ∕	<b>REGISTER BIT ALLOCATION</b>	NOI								Ŀ
p1	p2	p3	p4	p5	b6	p7	p8	6d	p8 p9 p10 p11	p11	p12	p13	p13 p14 p15 p16 p17	p15	p16	p17	p18	p18 p19 p20 p21	20 1	p21
dt16	dt15	dt14	dt13	dt12				DATA FIELD	IELD			dt4	dt3	dt2	dt1	dt0		ADDRESS	ESS	
								TEST BITS <sup>(2)</sup>	ITS <sup>(2)</sup>								0	0	0	0
×	×	×	×	OLP	OLA	CR1	CR0	×	×	sPON	CR1 CR0 X X SPON SAON X		×	×	×	×	0	0	0	-
PM16					٦	PRINCIP/	AL MA		IDER (	COEFF	INCIPAL MAIN DIVIDER COEFFICIENT					PM0	0	-	0	0
×	×	×	×	×	×	PR10		PRI	NCIPAL	. REFE	PRINCIPAL REFERENCE DIVIDER COEFFICIENT	IVIDER	COEFF	-ICIEN	 	PR0	0	-	0	-
×	×	×	AM13				AUXI	LIARY	MAIN	DIVIDE	AUXILIARY MAIN DIVIDER COEFFICIENT	FICIENT				AMO	0	-	-	0
×	×	×	×	×	×	<b>AR10</b>		AUX	<b>ILIARY</b>	, REFE	AUXILIARY REFERENCE DIVIDER COEFFICIENT	IVIDER	COEFF	FICIEN	 	AR0	0	-	-	-
×	×	×	×	×	×	×	×	×	0	DA6		7-E	7-BIT DAC			DA0	~	0	0	0

### Notes

FT = first; LT = last; sPON = software power-up for principal synthesizer (1 = ON); sAON = software power-up for auxiliary synthesizer (1 = ON). <del>.</del>.

The test register should not be programmed with any other value except all zeros for normal operation. ц Сі

# Table 3 Out-of-lock select

OUT-OF-LOCK ON PIN 20	output disabled	auxiliary phase error	principal phase error	both auxiliary and principal
OLA	0	1	0	1
OLP	0	0	Ţ	1

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DATA16 MSB

DATA15 p2

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LSB

DATA COEFFICIENT

p1

**FIRST IN** 

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LAST IN

ADD0 p21

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Table 4	Fast and normal	charge pumps	current ratio (note 1)	
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CR1	CR0	I <sub>CPA</sub>	I <sub>CPP</sub>	I <sub>CPPF</sub>	I <sub>CPPF</sub> : I <sub>CPP</sub>
0	0	$4  imes I_{SET}$	$4  imes I_{SET}$	$16  imes I_{SET}$	4 : 1
0	1	$4  imes I_{SET}$	$4  imes I_{SET}$	$32  imes I_{\text{SET}}$	8:1
1	0	$4  imes I_{\text{SET}}$	$2 \times I_{SET}$	$24  imes I_{SET}$	12 : 1
1	1	$4  imes I_{\text{SET}}$	$2 \times I_{SET}$	$32  imes I_{SET}$	16 : 1

#### Note

1. 
$$I_{SET} = \frac{V_{14}}{R_{ext}}$$
; common bias current for charge pumps and DAC.

#### Table 5Power-down modes

AON	PON	FAST	PRINCIPAL DIVIDERS	AUXILIARY DIVIDERS	PUMP CPA	PUMP CPP	PUMP CPPF	DAC AND BIAS
0	0	Х	OFF	OFF	OFF	OFF	OFF	OFF
0	1	0	ON	OFF	OFF	ON	OFF	ON
0	1	1	ON	OFF	OFF	ON	ON	ON
1	0	Х	OFF	ON	ON	OFF	OFF	ON
1	1	0	ON	ON	ON	ON	OFF	ON
1	1	1	ON	ON	ON	ON	ON	ON

#### Digital-to-analog converter

The 7-bits loaded via the bus into the appropriate latch drive a digital-to-analog converter. The internal current is scaled by the external resistance (R<sub>ext</sub>) at pin I<sub>SET</sub>, similar to the charge pumps. The nominal full-scale current is  $2 \times I_{SET}$ . The output current is mirrored to produce a full-scale voltage into a user-defined ground referenced resistance, thereby allowing optimum swing from power supply rails within the 2.7 to 5.5 V limits. The band gap reference voltage at pin I<sub>SET</sub> is temperature and supply independent. The DAC signal is monotonic across the full range of digital input codes to enable fine adjustment of other system blocks. The typical settling time for full-scale switching is 400 ns into a 12 k $\Omega$  // 20 pF load. DAC functionality is neither tested nor guaranteed on UMA1018M versions with the /S1 suffix.

#### Power-down modes

The action of the control inputs on the state of internal blocks is defined by Table 5.

It should be noted that in Table 5, PON and AON can be either the software or hardware power-down signals. The dividers are ON when both hardware and software power-down signals are at logic 1.

When either synthesizer is reactivated after power-down the main and reference dividers of that synthesizer are synchronized to avoid the possibility of random phase errors on power-up.

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#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>DD</sub>	digital supply voltage	-0.3	+5.5	V
V <sub>CC</sub>	analog supply voltage	-0.3	+5.5	V
$\Delta V_{CC-DD}$	difference in voltage between $V_{\mbox{CC}}$ and $V_{\mbox{DD}}$	-0.3	+5.5	V
V <sub>n</sub>	voltage at pins 1, 6, 8 to 15, 19 and 20	-0.3	V <sub>DD</sub> + 0.3	V
V <sub>2, 3, 17</sub>	voltage at pins 2, 3 and 17	-0.3	V <sub>CC</sub> + 0.3	V
$\Delta V_{GND}$	difference in voltage between AGND and DGND (these pins should be connected together)	-0.3	+0.3	V
P <sub>tot</sub>	total power dissipation	-	150	mW
T <sub>stg</sub>	storage temperature	-55	+125	°C
T <sub>amb</sub>	operating ambient temperature	-30	+85	°C
Tj	maximum junction temperature	-	95	°C

#### HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling MOS devices.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient in free air	120	K/W

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 $V_{DD1}$  =  $V_{DD2}$  = 2.7 to 5.5 V;  $V_{CC}$  = 2.7 to 5.5 V;  $T_{amb}$  = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply; pins	s 4, 5 and 18		•		-	
V <sub>DD</sub>	digital supply voltage	$V_{DD1} = V_{DD2}$	2.7	_	5.5	V
V <sub>CC</sub>	analog supply voltage	$V_{CC} \ge V_{DD}$	2.7	-	5.5	V
I <sub>DD</sub>	principal synthesizer digital supply current	V <sub>DD</sub> = 5.5 V	-	6.5	8.5	mA
	auxiliary synthesizer digital supply current	V <sub>DD</sub> = 5.5 V	-	2.7	4.0	mA
I <sub>CC</sub>	charge pumps and analog supply current	$V_{CC}$ = 5.5 V; R <sub>ext</sub> = 12 kΩ	-	1.2	2.0	mA
I <sub>CCPD</sub> , I <sub>DDPD</sub>	current in power-down mode per supply	logic levels 0 V or $V_{DD}$	-	12	50	μA
RF principal	l main divider input; pin 6					
f <sub>VCO</sub>	RF input frequency	2.7 V < V <sub>DD</sub> < 3.5 V	50	-	1250	MHz
		2.7 V < V <sub>DD</sub> < 5.5 V	50	-	1100	MHz
V <sub>6(rms)</sub> (RMS value)	R	$_{s} = 50 \Omega;$ 2.7 V < V <sub>DD</sub> < 3.5 V; 0.5 < f <sub>VCO</sub> < 1.25 GHz; T <sub>amb</sub> = -20 to +85°C	50	-	225	mV
		$R_{s} = 50 Ω;$ 2.7 V < V <sub>DD</sub> < 5.5 V; 0.5 < f <sub>VCO</sub> < 1.1 GHz; T <sub>amb</sub> = -30 to +85°C	100	-	300	mV
			150	_	300	mV
ZI	input impedance (real part)	f <sub>VCO</sub> = 1 GHz	_	1	_	kΩ
CI	typical pin input capacitance	indicative, not tested	-	2	-	pF
R <sub>pm</sub>	principal main divider ratio		512	-	131071	
f <sub>PPCmax</sub>	maximum principal phase comparator frequency		-	2000	-	kHz
f <sub>PPCmin</sub>	minimum principal phase comparator frequency		-	10	-	kHz

Product specification

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Auxiliary m	ain divider input; pin 15		ł		•	
f <sub>AI</sub>	input frequency		20	_	300	MHz
V <sub>15(rms)</sub>	AC-coupled input signal level (RMS value)	$ \begin{array}{l} {\sf R}_{\sf s} = 50 \; \Omega; \\ 2.7 \; {\sf V} < {\sf V}_{\sf DD} < 4.5 \; {\sf V}; \\ {\sf T}_{\sf amb} = -30 \; to \; +85^{\circ}{\rm C} \end{array} $	50	-	500	mV
			100	-	500	mV
ZI	input impedance (real part)	f <sub>AI</sub> = 100 MHz	-	1	-	kΩ
CI	typical pin input capacitance	indicative, not tested	-	2	-	pF
R <sub>am</sub>	auxiliary main divider ratio		64	_	16383	
f <sub>APCmax</sub>	maximum auxiliary phase comparator frequency		-	2000	-	kHz
f <sub>APCmin</sub>	minimum auxiliary phase comparator frequency		-	10	-	kHz
Crystal refe	erence divider input; pin 8					
f <sub>XTAL</sub>	crystal reference input frequency		5	-	40	MHz
V <sub>8(rms)</sub>	sinusoidal input signal level (RMS value)	4.0 V < V <sub>DD</sub> < 5.5 V	50	-	500	mV
		2.7 V < V <sub>DD</sub> < 5.5 V	50	_	250	mV
ZI	input impedance (real part)	f <sub>XTAL</sub> = 30 MHz	-	6	-	kΩ
CI	typical pin input capacitance	indicative, not tested	-	2	-	pF
R <sub>pr</sub>	principal reference divider ratio		8	-	2047	
R <sub>ar</sub>	auxiliary reference divider ratio		8	-	2047	
Charge pur	np current setting resistor input; p	bin 14				
R <sub>ext</sub>	external resistor from pin 14 to ground		12	-	60	kΩ
V <sub>14</sub>	regulated voltage at pin 14	$R_{ext} = 12 \ k\Omega$	-	1.15	-	V
Charge pur	np outputs; pins 17, 3 and 2; R <sub>ext</sub> =	<b>= 12 k</b> Ω				
I <sub>Ocp</sub>	charge pump output current error		-25	_	+25	%
I <sub>match</sub>	sink-to-source current matching	V <sub>cp</sub> in range	_	±5	-	%
I <sub>Lcp</sub>	charge pump off leakage current	$V_{cp} = \frac{1}{2}V_{CC}$	-5	±1	+5	nA
V <sub>cp</sub>	charge pump voltage compliance		0.4	-	V <sub>CC</sub> - 0.4	V
Interface lo	gic input signal levels; pins 13, 12	, 11 and 1				
V <sub>IH</sub>	HIGH level input voltage		0.7V <sub>DD</sub>	-	V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	LOW level input voltage		-0.3	_	0.3V <sub>DD</sub>	V
I <sub>bias</sub>	input bias current	logic 1 or logic 0	-5	_	+5	μA
CI	input capacitance	indicative, not tested	_	2	_	pF

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
DAC output signal levels; pin 10; $R_{ext}$ = 12 to 24 k $\Omega$							
I <sub>DAC</sub>	DAC full scale output current		$1.5  imes I_{SET}$	$2 \times I_{SET}$	$2.5  imes I_{\text{SET}}$	mA	
V <sub>10</sub>	output voltage compliance	all codes	0	-	V <sub>DD</sub> - 0.4	V	
I <sub>10min</sub>	minimum DAC current	00 code	_	2	5	μA	
I <sub>monot</sub>	worst case monotonicity test: $\Delta I \times \frac{128}{2 \times I_{SET}}$	note 1	0.1	_	1.9		
Lock detect	t output signal; pin 20; open-dra	in output					
V <sub>OL</sub>	LOW level output voltage	I <sub>sink</sub> = 0.4 mA	_	-	0.4	V	

#### Note

1. ∆I is the change in DAC output current when making the code transitions: 3FH/40H or 1FH/20H.

#### SERIAL BUS TIMING CHARACTERISTICS

 $V_{DD}$  =  $V_{CC}$  = 3 V;  $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT		
Serial programming clock; CLK							
t <sub>r</sub>	input rise time	-	10	40	ns		
t <sub>f</sub>	input fall time	-	10	40	ns		
T <sub>cy</sub>	clock period	100	-	-	ns		
Enable programming; E							
t <sub>START</sub>	delay to rising clock edge	40	-	-	ns		
t <sub>END</sub>	delay from last falling clock edge	-20	-	-	ns		
t <sub>W</sub>	minimum inactive pulse width	4000 <sup>(1)</sup>	-	-	ns		
t <sub>SU;Ē</sub>	enable set-up time to next clock edge	20	-	-	ns		
Register se	rial input data; DATA						
t <sub>SU;DAT</sub>	input data to clock set-up time	20	-	-	ns		
t <sub>HD;DAT</sub>	input data to clock hold time	20	-	-	ns		

#### Note

1. The minimum pulse width  $(t_W)$  can be smaller than 4  $\mu$ s provided all the following conditions are satisfied:

a) Principal main divider input frequency 
$$f_{VCO} > \frac{256}{t_W}$$

- b) Auxiliary main divider input frequency  $f_{AI} > \frac{32}{t_{W}}$
- c) Reference divider input frequency  $f_{XTAL} > \frac{3}{t_W}$



#### **APPLICATION INFORMATION**



